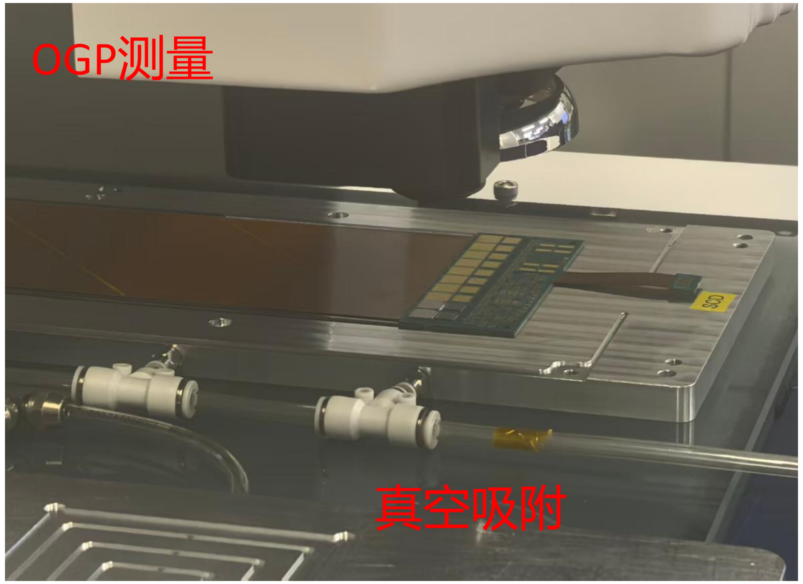
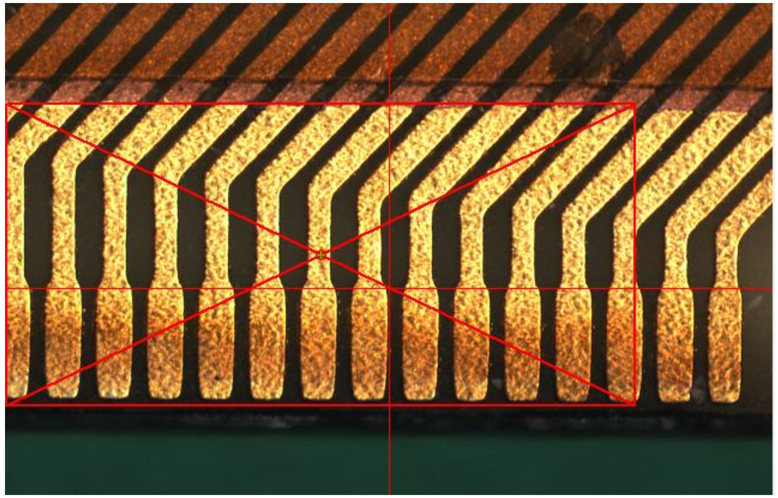
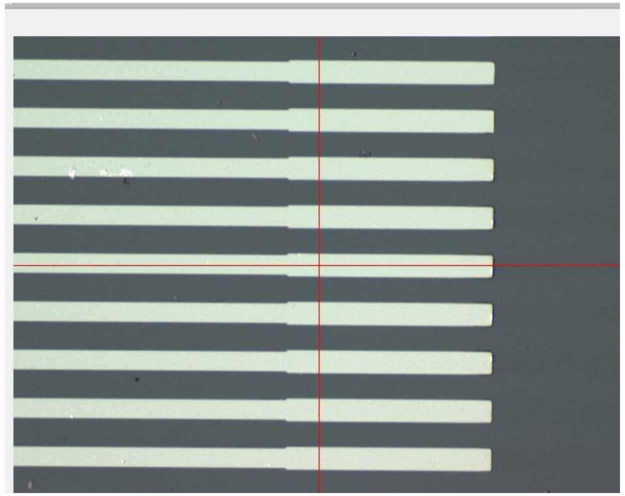
HERD STK/SCD group meeting

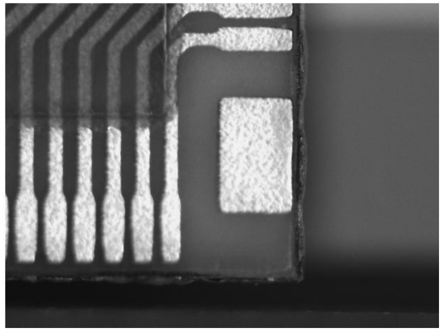
实验物理中心
金梁程龙
2026.01.09

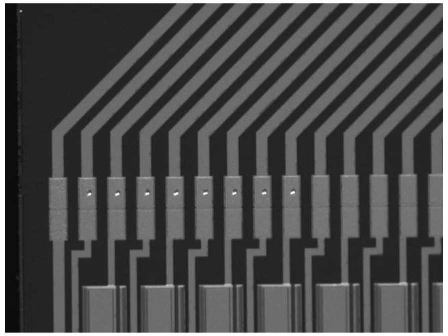
□SCD精度测量

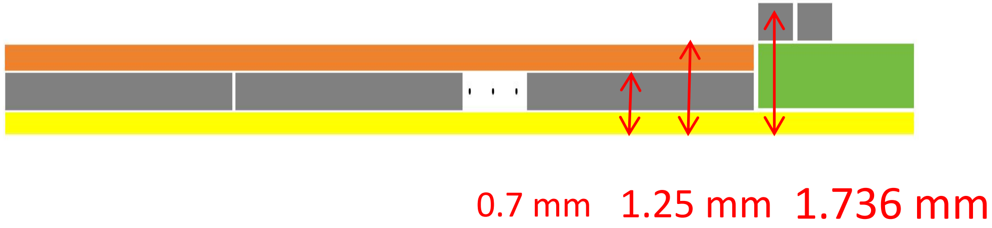




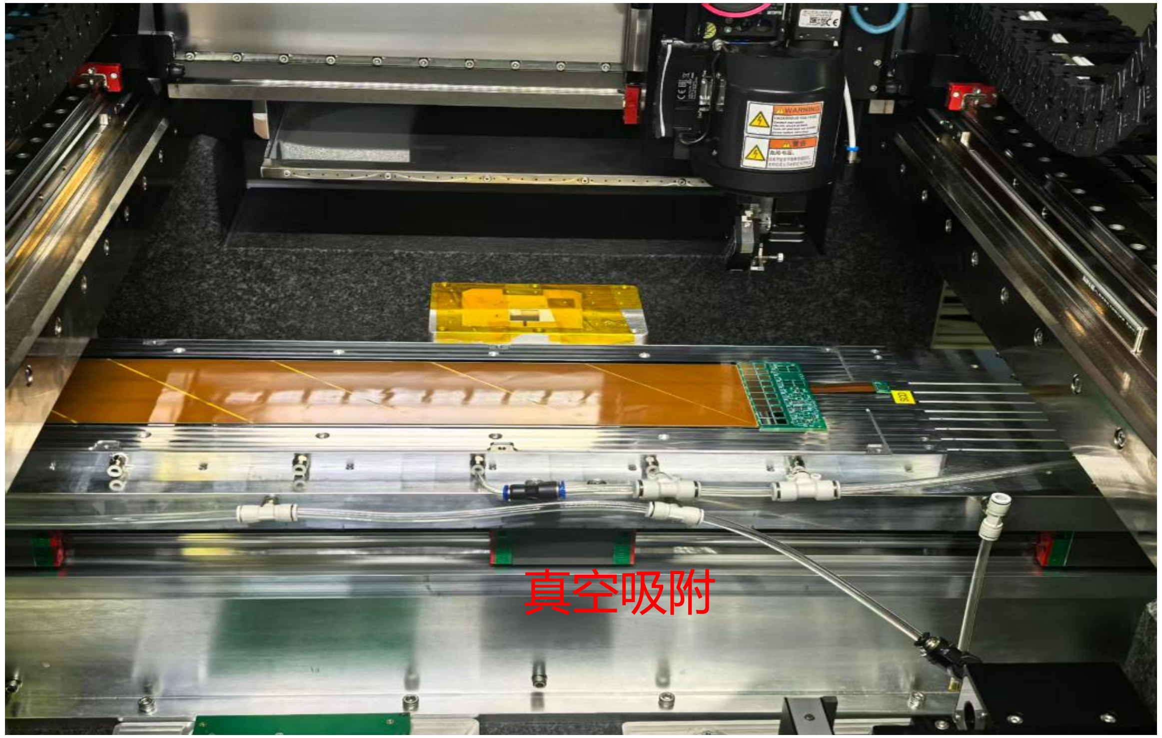


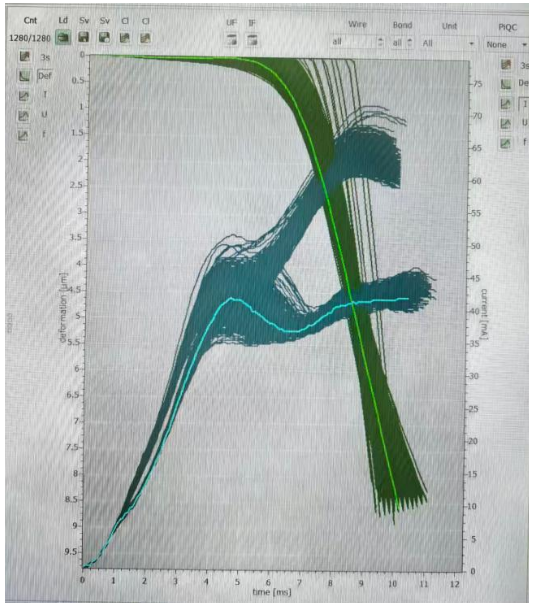


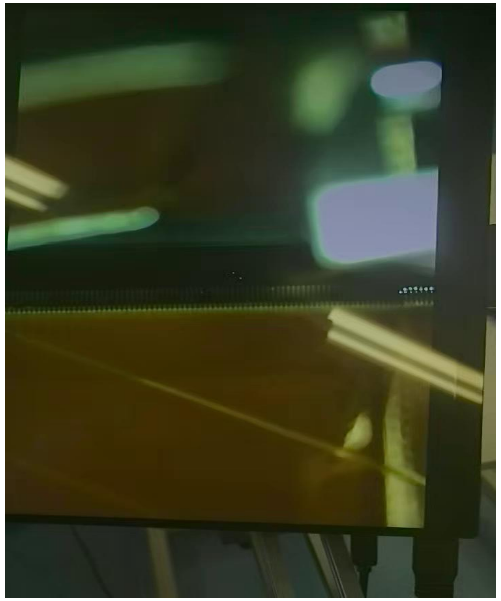


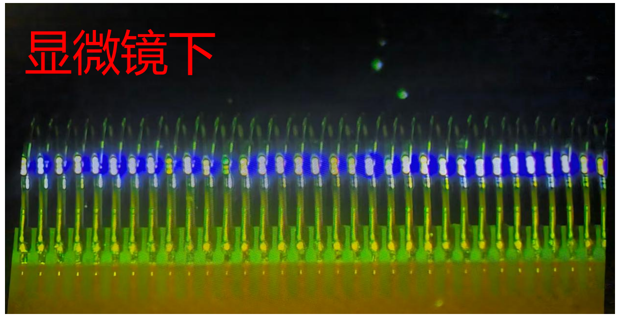


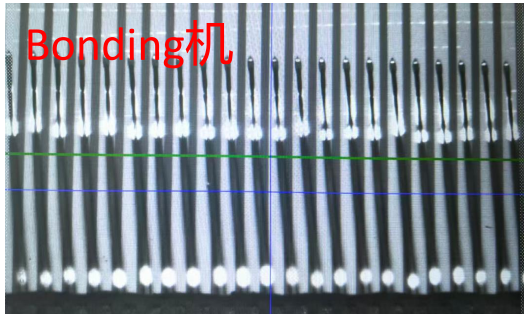
□Wire bonding





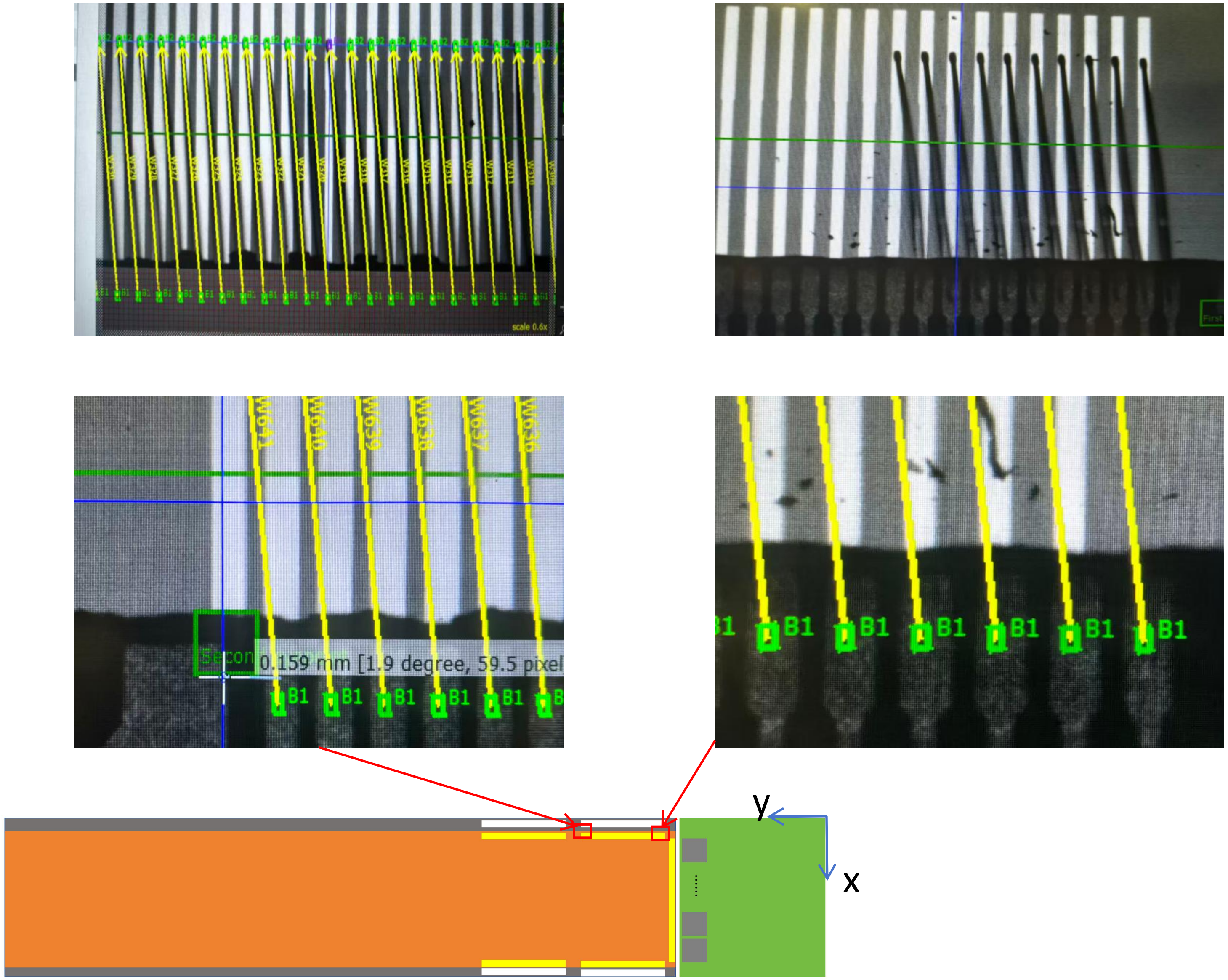


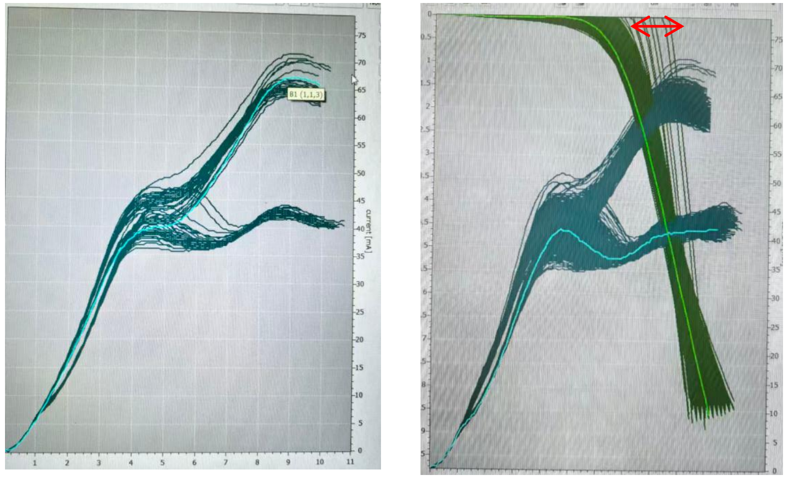




- 基于当前SCD dummy Z型 ladder，编写完成HERD FPC-SSD（上侧）的wire bonding程序，初步优化了键合参数
- 已完成一组SSD-FPC之间bonding（640根线，一次成功）
- 弧高参数设置866 μm，与OGP测量结果一致
- 下一步，完成FPC-电容之间程序编写，以及镜像位置的程序

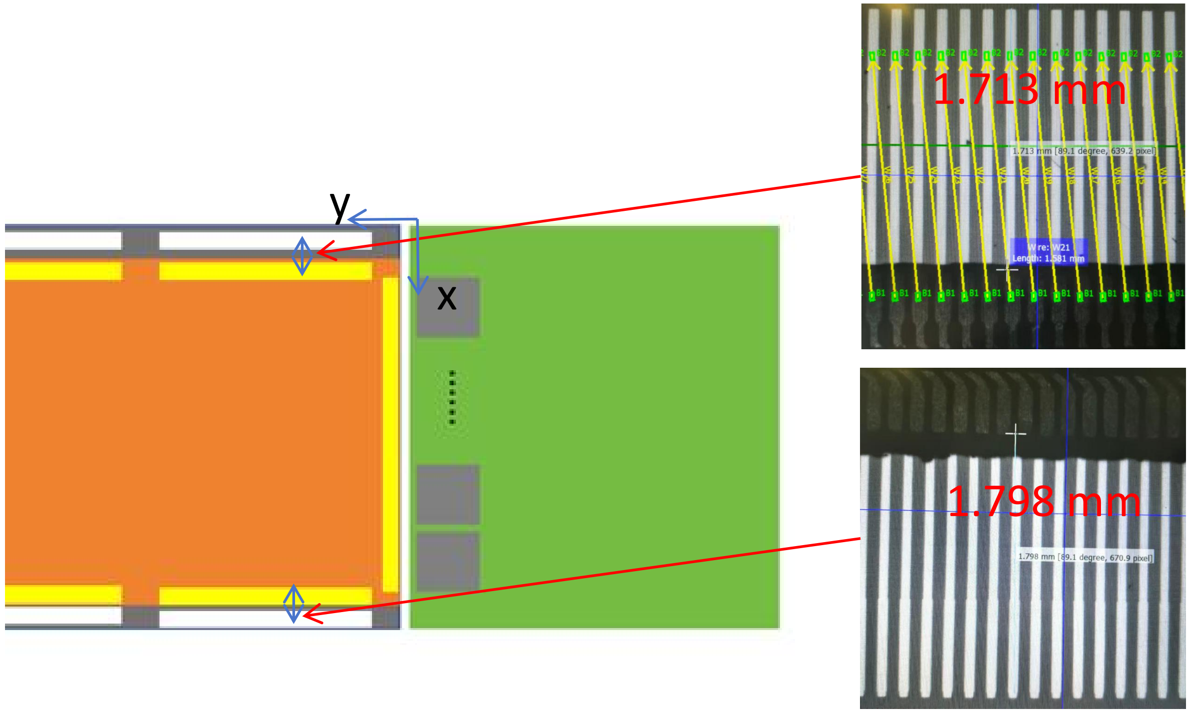
□FPC粘接精度测量

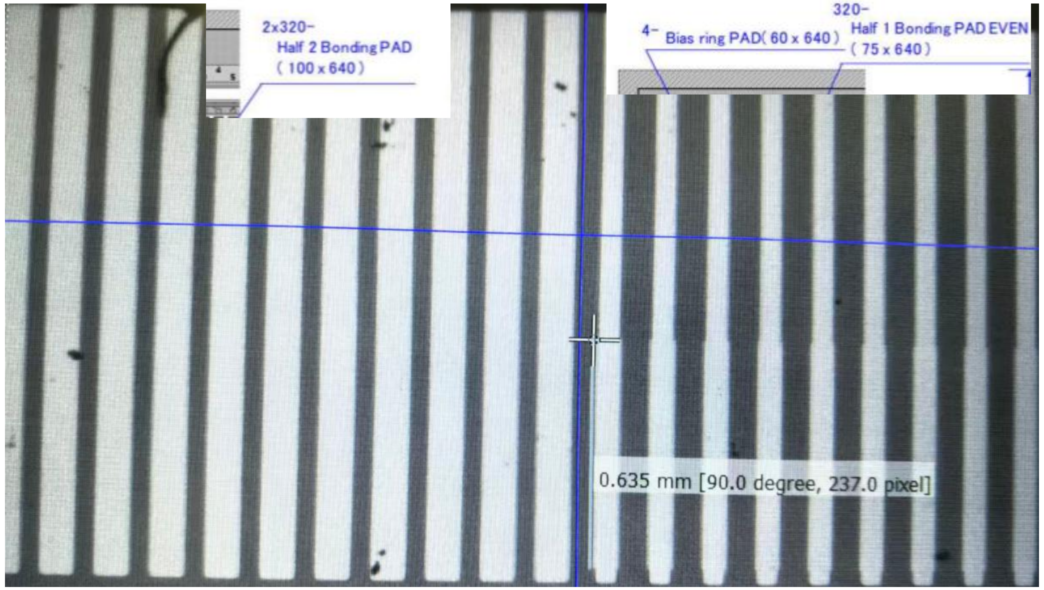




- y方向偏移一个pad（-159 µm）
- 靠近PCB边缘，FPC与SSD之间有明显间隙，导致键合稳定性较差（10根线左右）

□FPC粘接精度测量





- x方向偏移50 μm

- bonding机视角下，SCD SSD的pad边界不清晰
- 当前Dummy ladder的划痕较为严重

Thanks for your attention